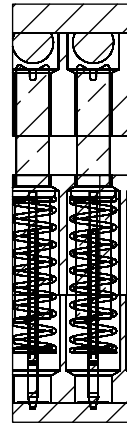
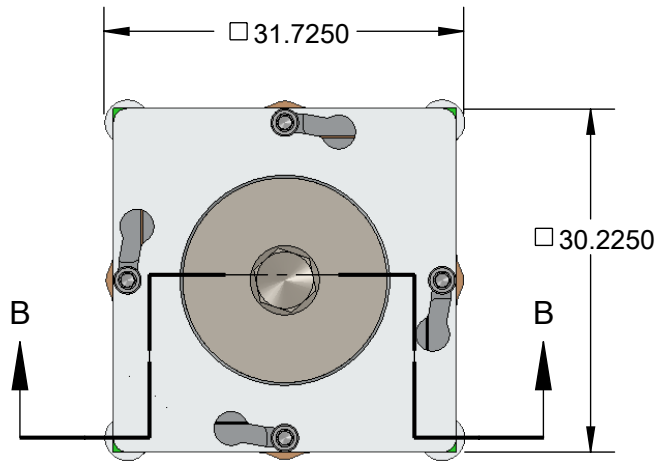


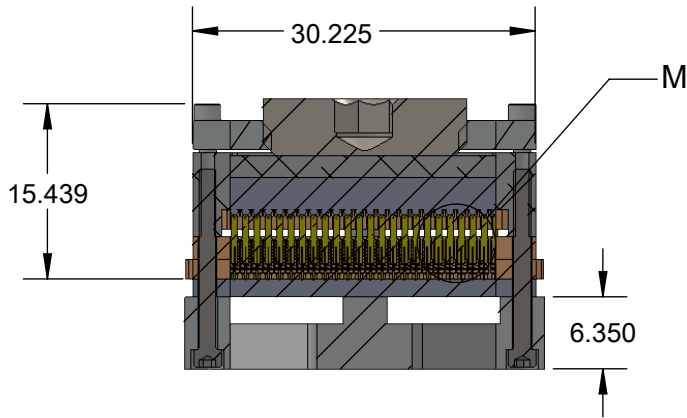
SBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS



DETAIL M
SCALE 8 : 1

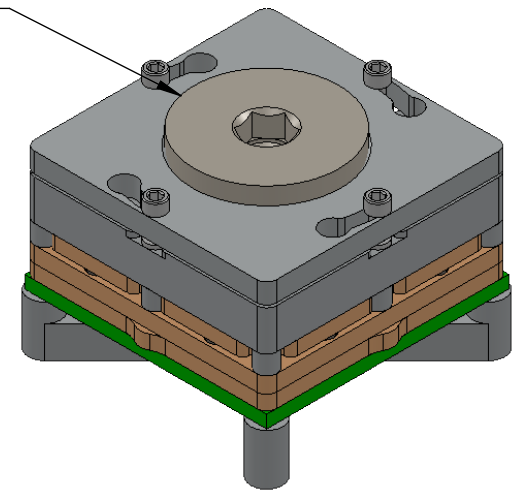
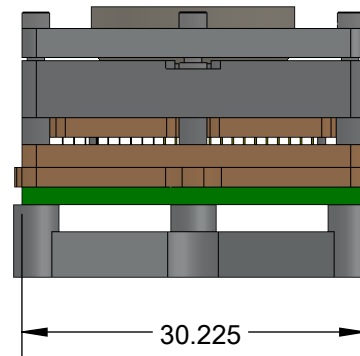
Features:

- Wide temperature range (-55C to +180C).
- High current capability (up to 4A).
- Excellent signal integrity at high frequencies.
- Low and stable contact resistance for reliable production yield.
- Highly compliant to accommodate wide co-planarity variations.
- Easily removable swivel lid



SECTION B-B


Apply Torque till Top guide touches the middle guide.
~ 59 N-cm [5.23 lbf-in]

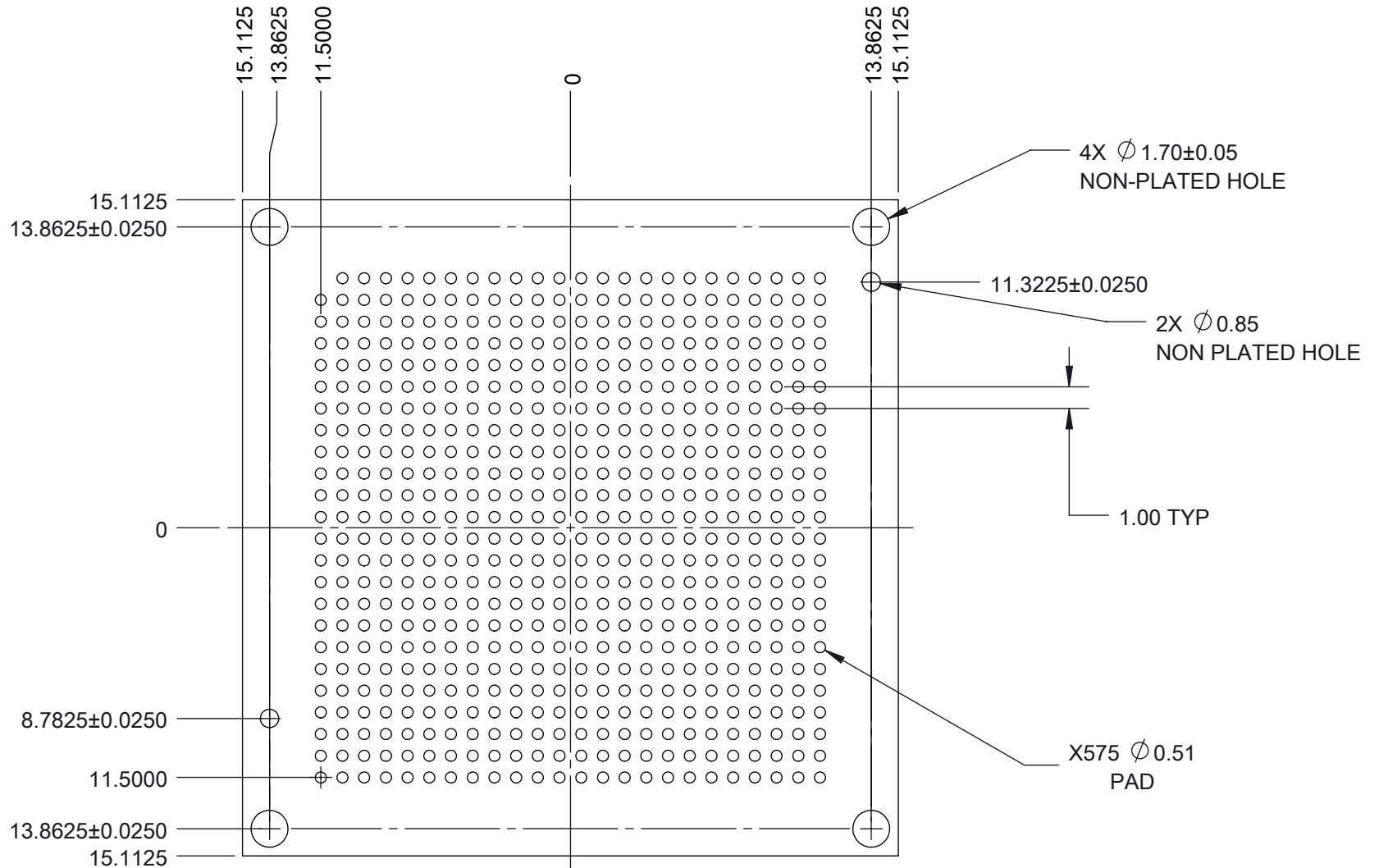


Description: SBT-BGA575 1MM 24x24 ARR SKT ASSEM

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [± 0.001 "], Pitches (from true position) $\pm 0.025\text{mm}$ [± 0.001 "], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

| | | | | |
|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------|-------------------------------------------------------------|---------------------------------------------------------|----------------------|
|  SBT-BGA-6530 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com | Material: N/A Finish: N/A Weight: 30.50 | STATUS: Released ENG: J. Vavra FILE: SBT-BGA-6530 Dwg | SHEET: 1 OF 4 DRAWN BY: M. Raske DATE: 11/10/2015 | REV. A SCALE: 3:2 |
| | | | | |



Description: Recommended PCB Layout

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.


Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

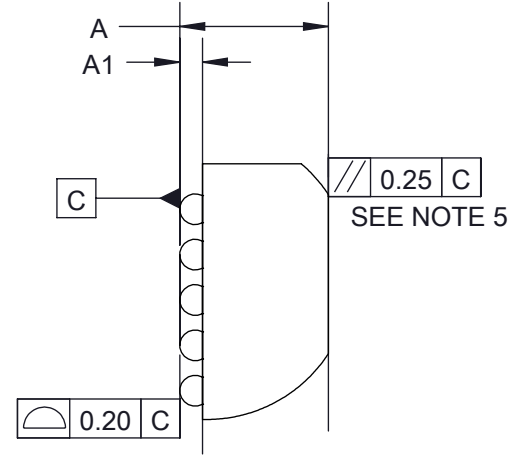
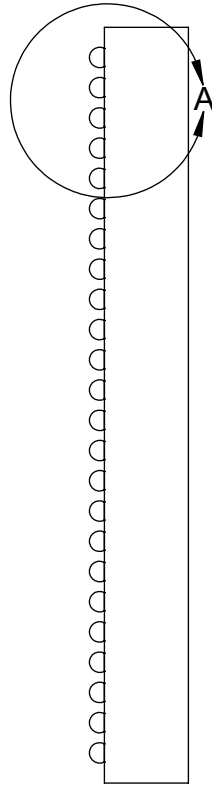
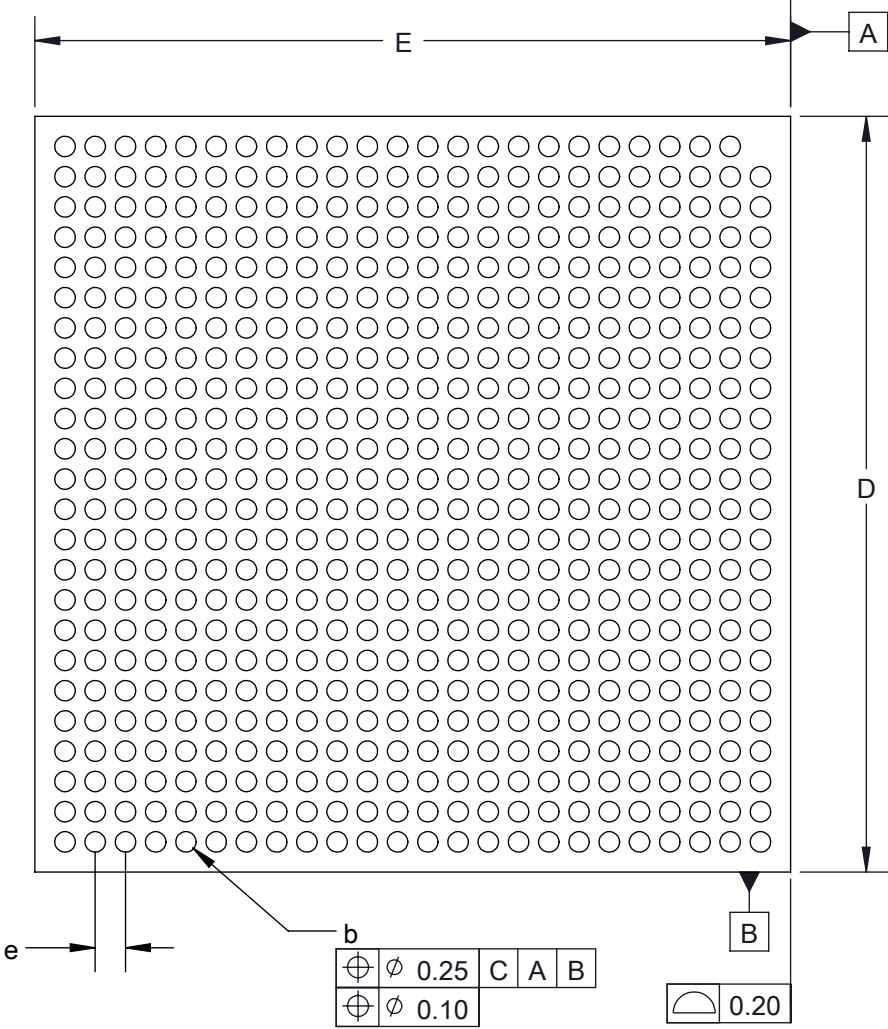
Target PCB Recommendations

Total thickness: 1.6mm min.

Plating: Gold or Solder finish

PCB Pad height: same or higher than solder mask

| | | | | |
|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------|------------------------|--------------------|--------------|
|  SBT-BGA-6530 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com | Material: N/A Finish: N/A Weight: 30.50 | STATUS: Released | SHEET: 2 OF 4 | REV. A |
| | | ENG: J. Vavra | DRAWN BY: M. Raske | SCALE: 3.5:1 |
| | | FILE: SBT-BGA-6530 Dwg | DATE: 11/10/2015 | |




DETAIL A
SCALE 6 : 1

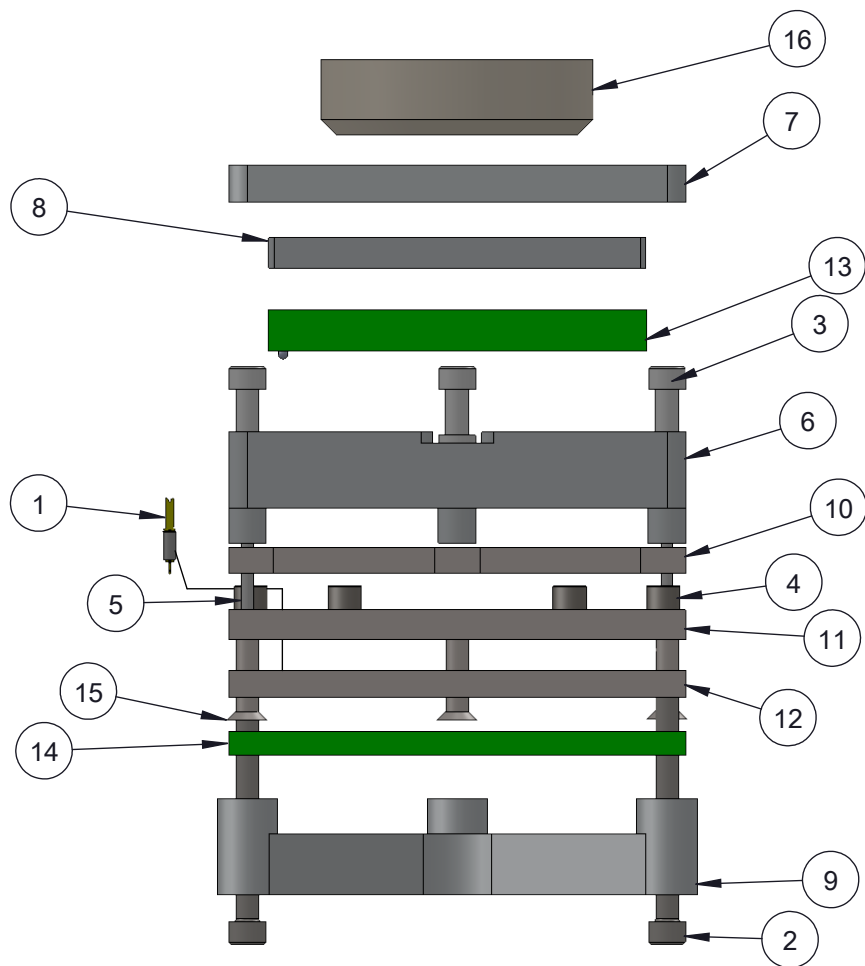
| DIM | Minimum | Maximum |
|-----------|-----------|---------|
| A | | 3.399 |
| A1 | 0.4 | 0.6 |
| b | 0.5 | 0.70 |
| D | 25.00 BSC | |
| E | 25.00 BSC | |
| e | 1.0 BSC | |
| ARRAY | 24 x 24 | |
| PIN COUNT | 575 | |

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

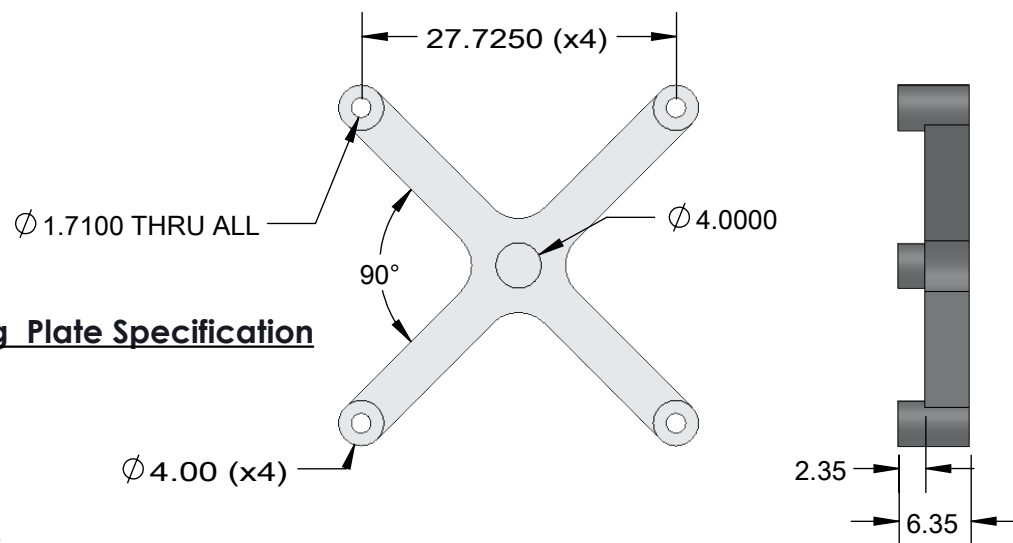
Description: Compatible BGA

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.
 Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

| | | | | |
|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------|-------------------------------------------------------------|---------------------------------------------------------|----------------------|
|  <p>SBT-BGA-6530 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com</p> | Material: N/A Finish: N/A Weight: 30.50 | STATUS: Released ENG: J. Vavra FILE: SBT-BGA-6530 Dwg | SHEET: 3 OF 4 DRAWN BY: M. Raske DATE: 11/10/2015 | REV. A SCALE: 4:1 |
| | | | | |



| ITEM NO. | DESCRIPTION | Material |
|----------|-----------------------------------------------------------|--------------------------|
| 1 | Pogo Pin, 1mm Pitch SBT BGA pin | |
| 2 | #0-80 X .625 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE | Alloy Steel |
| 3 | #0-80 Shoulder Screw, 1.59mm thread length | Stainless Steel (303) |
| 4 | Floating Guide Spring | Alloy Steel (SS) |
| 5 | Dowel Pin, 1/32" x 3/8", SS | Chrome Stainless Steel |
| 6 | SBT Ni Plt 25x25mm | 7075-T6, Plate (SS) |
| 7 | SBT Ni plt skt lid 25mm | 7075-T6 Aluminum Alloy |
| 8 | SBT COMP PLT NI PLT 25MM CSTM | 7075-T6, Plate (SS) |
| 9 | SBT/CBT Backing Plate 25mm IC | 7075-T6 Aluminum Alloy |
| 10 | Floating Guide 25x25mm 1mm 24x24 arr 575 holes | PEEK Ceramic filled |
| 11 | Middle Guide 25x25mm 1mm 24x24 arr 575 holes | PEEK Ceramic filled |
| 12 | Bottom Guide 25x25mm 1mm 24x24 arr 575 holes | PEEK Ceramic filled |
| 13 | BGA chip for 25x25mm 1mm, 24x24array | Material <not specified> |
| 14 | Target PCB for 25x25mm; 1mm, 24x24 | Material <not specified> |
| 15 | #0-80X0.25", 90 deg., head pin guide screw, Peek material | PEEK unfilled |
| 16 | Compression Screw, M18 | 7075-T6 Aluminum Alloy |




Backing Plate Specification

Description: Socket Assy, Insulation Plate

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

| | | | | |
|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------|------------------------|--------------------|------------|
|  SBT-BGA-6530 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com | Material: N/A Finish: N/A Weight: 30.50 | STATUS: Released | SHEET: 4 OF 4 | REV. A |
| | | ENG: J. Vavra | DRAWN BY: M. Raske | SCALE: 2:1 |
| | | FILE: SBT-BGA-6530 Dwg | DATE: 11/10/2015 | |